

IDENTIFYING FAULTY PROGRAMMABLE INTERCONNECT RESOURCES OF FIELD PROGRAMMABLE GATE ARRAYS

This application claims the benefit of U.S. Provisional Application No. 60/302,903, filed July 3, 2001.

Technical Field

The present invention relates generally to the field of integrated circuit devices and, more particularly, to a method of identifying faulty programmable interconnect resources of field programmable gate arrays.

5 Background of the Invention

A field programmable gate array (FPGA) is a type of integrated circuit consisting of an array of programmable logic blocks interconnected by a programmable interconnect network and programmable input/output cells. Programming of the logic blocks, the interconnect resources which make up
10 the network, and the input/output cells is selectively completed to make the

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Fig. 1

necessary interconnections that establish one configuration thereof to provide the desired system operation/function for a particular application.

The present inventors have recently developed off-line methods of built-in self-testing the array of programmable logic blocks and the programmable interconnect resources in FPGAs at the device, board and system levels. These methods are set out in detail in U.S. Patent Nos. 5,991,907, 6,003,150, 6,108,806, and 6,202,182. The full disclosures in these patents are incorporated herein by reference.

In addition to these off-line testing methods, the present inventors have also recently developed methods of testing and fault tolerant operation of the programmable logic blocks and methods of testing the programmable interconnect resources during normal on-line operation of the FPGAs. These testing and operating methods are set out in detail in U.S. Patent No. 6,256,758 and in pending U.S. Application Nos. 09/405,958, 09/671,853, 09/406,219, and 09/611,449. The full disclosures in this patent and patent applications are also incorporated herein by reference.

On-line testing and fault tolerant operation of FPGAs is most important in high-reliability and high-availability applications, such as, long-life space missions, telecommunication network routers, or remote equipment in which adaptive computing systems often rely on reconfigurable hardware to adapt system operation to environment changes. In such applications, the FPGA hardware must work continuously and simply cannot be taken off-line for testing, maintenance, or repair.

When faults are detected in the programmable interconnect resources of the FPGA hardware of these systems, the faulty resources must be quickly

identified in order to facilitate efficient reconfiguration of the remaining FPGA resources to avoid the faulty resources, or to reuse the faulty resources for fault-tolerant operation of the FPGA. Accordingly, a need is identified for an efficient and adaptive method of identifying faulty programmable interconnect resources which may be performed concurrently with normal system operation or during manufacturing testing.

Summary of the Invention

In accordance with the present invention, a method of identifying faulty programmable interconnect resources of a field programmable gate array (FPGA) may be carried out during normal on-line operation and/or during manufacturing testing. The FPGA resources are configured into a working area and a self-testing area. The working area maintains normal operation of the FPGA throughout on-line testing. During manufacturing testing, the working area may be replaced with additional self-testing areas or the self-testing area extended to include the entire FPGA. Within the self-testing area, the programmable interconnect resources are tested for faults and faulty interconnect resources identified. It is initially presumed that all of the resources of the FPGA are fault-free as determined through manufacturing testing.

To test the programmable interconnect resources, test patterns are generated and applied to programmable interconnect resources selected for testing. Outputs of a first group of selected programmable interconnect resources, or wires under test, are preferably compared to outputs of a second

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group of wires under test. Based on a comparison of the outputs of the groups of wires under test, fault status data is generated.

The first and second groups of wires under test may be further compared to at least a third group of wires under test. Based on a comparison of the outputs of the first group of wires under test with the third group, for example, the presence of the at least one faulty resource within either the first or second group of wires under test may be determined. Whether or not the fault is identified within the first group of wires under test through comparison to the third group of wires under test, the second group of wires under test may also be compared to the third, or a different group of wires under test, to determine whether multiple faults are present, i.e., to insure that the second group of wires under test are fault-free.

Once a group of wires under test containing a faulty programmable interconnect resource is identified, the FPGA resources within the self-testing area of the FPGA under test may be reconfigured into subsequent groups of wires under test for further testing in order to minimize a region of the group of wires under test which includes the faulty interconnect resource. Specifically, the group of wires under test which includes the faulty interconnect resource may be subdivided and its interconnect resources grouped with additional known fault-free resources to form the subsequent groups of wires under test. The subsequent groups of wires under test may be further comparatively tested in the manner described above. These steps of testing and reconfiguring may be repeated until the region of the group of wires under test which includes the faulty interconnect resource is minimized.

Depending upon which interconnect resources are being tested, an

alternate method of testing the programmable interconnect resources with the faulty group of wires under test (or a combination of the two methods) may be utilized to minimize the region of the group of wires under test which includes the faulty resource. Specifically, the FPGA resources within the self-testing area may be configured such that comparisons of the output patterns of regions of the groups of wires under test may be made at several locations along the groups of wires under test and fault status data for each region may be produced. In this manner, the region of the group of wires under test containing the faulty interconnect resource may be minimized without subdividing the group of wires under test as described above.

Once a region of the groups of wires is identified as including the faulty resource in the alternate method, the direction of propagation of the test patterns along the groups of wires under test may be reversed allowing the identified region of the group of wires to be further reduced, or a determination made that multiple interconnect resources may be faulty. If there are multiple faulty resources, the group of wires under test may then be subdivided and tested as described above in order to separate the multiple faulty resources for further testing. Once separated, the FPGA resources within the self-testing area may be reconfigured into subsequent groups of wires under test for further testing in order to isolate regions of the groups of wires under test which include the faulty interconnect resources in the manner described above.

Once the region from the group of wires under test containing a faulty programmable interconnect resource is minimized, the FPGA resources within the self-testing area of the FPGA under test may be reconfigured into

subsequent groups of wires under test for further testing in order to identify which wire within the minimized region of the group of wires under test includes the faulty interconnect resource. Specifically, the wires of the region of the group of wires under test which includes the faulty interconnect resource may be subdivided and grouped with additional known fault-free resources to form the subsequent groups of wires under test. The subsequent groups of wires under test are further comparatively tested in the manner described above. These steps of testing and reconfiguring may be repeated until the wire within the minimized region of the group of wires under test includes the faulty interconnect resource is identified.

In accordance with the broad teachings of the present invention, the steps of minimizing a region of the group of wires under test and identifying which wire in the group of wires under test includes the faulty interconnect resource may be conducted in any order. For example, once a group of wires under test containing a faulty programmable interconnect resource is identified, the FPGA resources within the self-testing area of the FPGA under test may be reconfigured into subsequent groups of wires under test for further testing in order to identify which wire in the group of wires under test includes the faulty interconnect resource in the manner described above. Once the wire of the group of wires under test is identified, a region of the identified wire which includes the faulty interconnect resource may be minimized in the manner described above.

Once the region of the group of wires under test which includes the faulty interconnect resource is minimized and the wire within the group of wires identified, the FPGA resources within the self-testing area are again

reconfigured to test the interconnect resources, i.e., the wire segments and/or configurable interconnect points, within the minimized region of the identified wire in order to identify the faulty interconnect resource or combination of resources. Specifically, portions of the faulty region of the identified wire are re-routed using known fault-free wires and/or configurable interconnect points to avoid suspect faulty wire segments or configurable interconnect points and further tested. These steps of re-routing and testing may be repeated until the faulty wire and/or configurable interconnect point is identified.

In accordance with another aspect of the present invention, the self-testing area of the FPGA under test may be reconfigured so that a portion of the working area becomes a subsequent self-testing area, and at least a portion of the initial self-testing area becomes a portion of the working area once testing of the resources in the self-testing area of the FPGA under test is completed and any faulty interconnect resource identified. In other words, the self-testing area may rove around the FPGA under test repeating the steps of testing, reconfiguring, and identifying faulty interconnect resources within the self-testing areas while normal operation of the FPGA under test continues within the working areas uninterrupted by the activities conducted within the roving self-testing area.

An apparatus for identifying faulty programmable interconnect resources of an FPGA under test during normal on-line operation includes a test and reconfiguration controller in communication with the FPGA under test for: (a) configuring the field programmable gate array into a self-testing area and a working area, the working area maintaining normal operation of

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the field programmable gate array; (b) initiating testing of groups of programmable interconnect resources located within the self-testing area for faults; (c) reconfiguring groups of resources determined to include a faulty resource for further testing in order to minimize a region of the group of resources which includes the faulty resource; (d) repeating the steps of testing and reconfiguring until the region of the group of resources which include the faulty resource is minimized; (e) reconfiguring the resources located within the minimized faulty region of the group of resources for further testing in order to identify the faulty resource by re-routing portions of the minimized faulty region to avoid suspect resources; and (f) repeating the steps of reconfiguring and further testing until the faulty resource is identified. The testing apparatus further includes a storage device or medium in communication with the test and reconfiguration controller for storing a plurality of test configurations, and usage and fault status data for each FPGA resource.

Brief Description of the Drawings

The accompanying drawings incorporated in and forming a part of the specification, illustrate several aspects of the present invention and together with the description serve to explain the principles of the invention. In the drawings:

Figure 1 is a schematic block diagram of an apparatus for testing resources of a field programmable gate array (FPGA);

Figure 2 is an illustration of an FPGA under test configured into a self-

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Figure 9 is a schematic block diagram of a tester for comparing a minimized region of the group of wires under test to a known fault-free wire;

Figure 11 is a schematic block diagram showing a group of interconnect resources used for explanation purposes.

Reference will now be made in detail to the present preferred embodiment of the invention, an example of which is illustrated in the accompanying drawings.

Detailed Description of the Invention

5 A typical field programmable gate array (FPGA) generally consists of a plurality of resources including an array of programmable logic blocks (PLBs) interconnected by a programmable interconnect network, and programmable input/output cells or boundary scan ports (most FPGAs feature a boundary-scan mechanism). Such structures are, for example, featured in
10 Agere Systems' ORCA Series FPGAs, in the Xilinx VIRTEX Series FPGAs, and in the Altera FLEX 8000 logic devices. In accordance with a preferred embodiment of the present inventive method, programmable interconnect resources which make up the interconnect network of an FPGA under test
15 are tested for faults and faulty interconnect resources identified in an efficient and adaptive manner during normal on-line operation of the FPGA under test 10.

 As shown in schematic block diagram in Figure 1, the present method of identifying faulty programmable interconnect resources is preferably controlled by a test and reconfiguration controller 12. Most preferably, an
20 external test and reconfiguration controller 12 is utilized because present commercially available FPGAs do not provide internal access to their configuration memory. Accordingly, a configuration decompiler tool of a type known in the art is utilized to determine the intended function or mode

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of operation of the FPGA resources. Alternatively, this information may be extracted from the design stage and made available to the controller 12. It should be appreciated by those skilled in the art that any controller, e.g., internal or external to an FPGA, could be utilized with an FPGA that allows for internal access to its configuration memory and that a single test and reconfiguration controller is capable of controlling several FPGAs. For purposes of illustration of the present preferred embodiment of the invention, however, a one-to-one controller to FPGA ratio is utilized.

The preferred controller 12 may be implemented on a microprocessor in communication with a storage medium or memory 14 for storing the various FPGA operational and test configurations, as well as, fault status data for the FPGA resources, or a standard piece of test equipment. In operation, the controller 12 accesses the FPGA under test 10 using its boundary-scan interface in a known manner such that access is transparent to normal function of the FPGA 10. Specifically, the controller 12 uses the boundary-scan interface to configure the FPGA resources for testing, to initiate testing of the FPGA resources, and to scan out the test results. As shown in Figure 2, the FPGA under test 10 is initially configured by the controller 12 into a self-testing area 16 and a working area 18. In accordance with an important aspect of the present invention, normal operation of the FPGA under test 10 is maintained within the working area 18 while the programmable interconnect resources are tested and faulty resources identified in the self-testing area 16. During manufacturing testing, the working area may be replaced with additional self-testing areas or the self-testing area extended to include the entire FPGA.

Testing of the FPGA 10 is generally accomplished by configuring its resources within the self-testing area 16 to function as a test pattern generator (TPG) 20 and an output response analyzer (ORA) 22, and as groups of interconnect resources or wires under test (WUTs) 24 as shown in Figure 3.

5 During testing, an exhaustive set of equivalent test patterns generated using the TPG 20 is applied to and propagated along the groups of WUTs 24. Most preferably, the TPG 20 utilized to generate the exhaustive set of test patterns is configured as an n-bit counter. The groups of WUTs 24 may include wire segments 26, configurable or configuration interconnect points (CIPs) 10 (including cross point CIPs 28 for connecting wire segments located in disjoint planes and break-point CIPs 29 for connecting wire segments in the same plane), and programmable logic blocks (PLBs) 30. Preferably the groups of WUTs 24 initially extend along the length of the self-testing area 16.

15 Outputs of the groups of WUTs 24 are compared by the ORA 22 to determine whether a fault exists within either of the groups of WUTs 24. A match/mismatch result of the comparison performed by the ORA 22 is communicated as a pass/fail result or fault status data through the boundary-scan interface of the FPGA under test to the controller 12. The fault status 20 data is stored in memory 14 and utilized by the controller 12 in reconfiguring the FPGA resources for further testing.

In order to minimize the number of reconfigurations required during testing and therefore the total testing time, the FPGA resources within the self-testing area 16 are preferably configured to include several testing 25 regions 19 (Region₁, Region₂, . . . Region_n) as shown in Figure 4. Necessarily

each tester 19 includes at least a TPG 20, an ORA 22, and two groups of WUTs 24. Comparative testing of the interconnect resources within each tester 19 is conducted concurrently. The present preferred comparison-based on-line method of testing the programmable interconnect resources briefly described above including the fault model utilized and configuration of the self-testing area is described in detail for programmable interconnect resources in the above-referenced pending U.S. Application No. 09/406,219 and in C. Stroud ET AL., *Built-In Self-Test of FPGA Interconnect*, PROC. INTN'L TEST CONF., at 404-411, 1998 incorporated herein by reference. As indicated above, the present preferred method may target permanent faults that exist in a newly manufactured FPGA device or which appear during the lifetime of the FPGA under test.

In order to avoid potential problems caused by equivalent faults in the groups of WUTs being compared in each tester, the test patterns propagated along a first group of WUTs 32 are preferably compared to test patterns propagated along two different groups of WUTs. As shown in Figure 5, for example, the test patterns propagated along a first group of WUTs 32 are compared to the test patterns propagated along a second group of WUTs 33 in the same tester 34, and subsequently to test patterns propagated along a third group of WUTs 35 from a different tester 37. In addition, the test patterns propagated along the second group of WUTs 33 are similarly compared to test patterns propagated along a third group of WUTs from a different tester, such as the third group of WUTs 35 from the tester 37. Advantageously, these secondary comparisons substantially eliminate the potential problem of equivalent faults within the groups of WUTs and, in

accordance with an important aspect of the present invention, provide an indication as to which of the first or second group of WUTs 32 or 33 within the tester 34, or both, contain the faulty interconnect resource or resources.

When the fault status data indicates the detection of a fault in one of the testing regions 19 in the self-testing area 16, roving of the self-testing area 16 is temporarily interrupted. In other words, the controller 12 stops or parks the self-testing area 16 over the testing region 19 suspected of containing the faulty interconnect resource. In this manner, the faulty interconnect resource may be identified while normal operation of the FPGA under test 10 continues in the working area 18.

Once a group of WUTs 32 is identified as including a faulty programmable interconnect resource, the resources of the FPGA under test 10 within the self-testing area 16 are reconfigured for further testing in order to minimize a region of the group of WUTs 32 which includes the faulty interconnect resource. Preferably, the group of WUTs 32 containing the faulty resource is reconfigured into subsequent groups of WUTs 32a and 32b as shown in Figure 6 for further comparative testing. The subsequent groups of WUTs 32a, 32b are further tested in order to minimize a region of the group of WUTs 32 which includes the faulty interconnect resource. Specifically, the suspect group of WUTs 32 is subdivided and its interconnect resources grouped with additional known fault-free resources to form the two subsequent groups of WUTs 32a, 32b. The programmable interconnect resources in each subsequent group of WUTs 32a, 32b are independently comparatively tested in new testing regions 35, 36 in the manner described above. Dependent upon the subsequent fault status data, the interconnect

resources within one or both of the subsequent groups of WUTs 32a, 32b may be further reconfigured or subdivided, and tested until the region (or regions in the case of multiple faults) of the group of WUTs 32 which includes the faulty programmable interconnect resource is minimized. In other words, the steps of testing and reconfiguring may be repeated until the region of the group of WUTs 32 which includes the faulty interconnect resource cannot be further subdivided.

Depending upon which interconnect resources are being tested, an alternate method of testing the programmable interconnect resources within the faulty group of wires under test (or a combination of the two methods) may be utilized to minimize the region of the group of wires under test which includes the faulty resource. As shown in Figure 7, the FPGA resources within the self-testing area 16 may be configured such that comparisons of the output patterns of regions of the groups of wires under test 37, 38 may be made by ORAs 22 at several locations along the groups of wires under test and fault status data for each region may be produced. In this manner, the region of the group of wires under test containing the faulty interconnect resource may be minimized without subdividing the group of wires under test as described above.

Once a region of the groups of wires is identified as including the faulty resource in the alternate method, the direction of propagation of the test patterns along the groups of wires under test 37, 38 may be reversed allowing the identified region of the group of wires to be further reduced, or a determination made that multiple interconnect resources may be faulty. If there are multiple faulty resources, the group of wires under test 37, 38 may

then be subdivided and tested as described above in order to separate the multiple faulty resources for further testing. Once separated, the FPGA resources within the self-testing area 16 may be reconfigured into subsequent groups of wires under test for further testing in order to minimize regions of the groups of wires under test which include the faulty interconnect resources in the manner described above.

Once it becomes impractical to further subdivide the region of the group of WUTs 32 which includes the faulty interconnect resource, the resources of the FPGA under test 10 are again reconfigured in order to identify a wire $32a_1, 32a_2, \dots 32a_n$ of the minimized region of the group of WUTs 32a, for example, which includes the faulty interconnect resource. Specifically as shown in Figure 8, the wires $32a_1, 32a_2, \dots 32a_n$ of the suspect group of WUTs 32a are grouped with additional known fault-free resources to form two subsequent groups of WUTs which are comparatively tested in new testing regions 35a, 35b, $\dots 35n$ in the manner described above. Dependent upon the subsequent fault status data, the wires $32a_1, 32a_2, \dots 32a_n$ may be further reconfigured and tested until the wire of the minimized region of the group of WUTs 32a which includes the faulty programmable interconnect resource is identified. In other words, the steps of testing and reconfiguring may be repeated until the wire (e.g., $32a_1$) of the minimized region of the group of WUTs 32a which includes the faulty interconnect resource is identified.

In accordance with the broad teachings of the present invention, the steps of minimizing a region of the group of wires under test and identifying which wire in the group of wires under test includes the faulty interconnect

resource may be performed in any order. For example, once a group of wires under test containing a faulty programmable interconnect resource is identified, the FPGA resources within the self-testing area of the FPGA under test may be reconfigured into subsequent groups of wires under test for further testing in order to identify which wire in the group of wires under test includes the faulty interconnect resource in the manner described above. Once the wire of the group of wires under test is identified, a region of the identified wire which includes the faulty interconnect resource may be minimized in the manner described above.

Once the region of the WUTs is minimized and the wire identified, a variety of testing configurations may be adaptively utilized to identify the faulty interconnect resource within the faulty region of the wire. In order to more precisely identify which interconnect resource, i.e., which wire segment or configuration interconnect point (CIP), within the faulty region is faulty, further reconfiguration and comparative testing is required.

In accordance with the preferred embodiment of the present invention, the faulty region of the identified wire is compared to a second group of interconnect resources containing only known fault-free resources in the manner described above. As shown in Figure 9, for example, the resources in the faulty region 38 may include wire segments 42, 44, and 46 and CIPs 41, 43, 45, and 47. The second group of interconnect resources 39 may include a single known fault-free wire 40 or a group or interconnect resources. In order to identify which interconnect resource within the faulty region 38 is faulty, additional known fault-free resources are combined with the resources in the faulty region 38 in order to circumvent one suspect

resource at a time.

As shown in Figure 10, for example, the additional fault-free resources 49, 50, 51, 52, and 53 may be utilized to re-route the resources within the faulty region 38 to avoid a selected suspect resource (e.g., 46) one at a time during testing. In other words, the additional fault-free resources 49, 50, 51, 52, and 53 are utilized to re-route the resources within the faulty region 38 such that the suspected faulty resource, i.e., wire segment 46 is removed from the faulty region 38 during the comparative testing. The steps of re-routing and testing are repeated until each interconnect resource in the faulty region 38 is removed from the faulty region 38 during testing.

Although a preferred method for identifying faulty interconnect resources is broadly set out above, it must be appreciated that the steps utilized to identify a faulty interconnect resource within a faulty region depend both on the type of fault, e.g., an open, a short, etc., and the type of interconnect resources included in the faulty region. The following example is provided to better illustrate this point and the present invention.

Before providing the noted example, however, it must first be understood that the definition of a wire segment varies dependent upon the type of fault associated therewith. A wire segment for an open fault is defined as a wire bounded by any two CIPs (including cross-point and breakpoint CIPs) with no other CIPs in between. A wire segment for a short fault, on the other hand, is defined as a wire(s) bounded by breakpoint CIPs.

Referring to Figure 11, for example, wire segments are represented by numerals 55, 56, and 57 when the fault is an open fault. Wire segment 55 is bound by a breakpoint CIP 58 and a cross-point CIP 59, wire segment 56 is

bound by cross-point CIPs 59 and 60, and wire segment 57 is bound by cross-point CIP 60 and breakpoint CIP 61. The reason for this definition is that an open in any of these wire segments 55, 56, or 57 can be uniquely identified using the above-described re-routing steps. For example, assume that the

5 bold solid line (or signal net) routed through cross-point CIP 59, wire segment 56, and cross-point CIP 60 represents a group of WUTs 62 in an FPGA under test. This group of WUTs may be used to test wire segment 56 for an open fault even though wire segments 55, 57, 63, and 64 are connected to the same signal net 62 through cross-point CIPs 59 and 60 respectively.

10 These wire segments 55, 57, 63, and 64 connect the group of WUTs 62 to other wire segments in the interconnect network due to the function of the cross-point CIPs 59 and 60 which does not break continuity along horizontal and vertical wires like breakpoint CIPs. Similarly, wire segments 55 and 57 may be tested for an open fault by reconfiguring the interconnect resources

15 and more specifically creating new groups of WUTs which include wire segments 65, 55, and 64 and 63, 57 and 66, respectively.

Further reconfigurations and testing may be utilized to identify the faulty interconnect resource, i.e., whether the open fault is in a wire segment or an adjacent CIP, in some scenarios depending upon where the open fault

20 actually resides. If the open fault is in wire segment 56 which is positioned between two cross-point CIPs 59 and 60, for example (shown in Figure 11), further reconfiguration(s) and testing may identify that the CIPs are in working order and that the open fault resides in the wire segment 56. If the open fault resides in one of the CIPs 59 or 60 as a stuck-open fault, then a

25 determination of whether the open fault resides in the wire segment 56 or an

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adjacent CIP 59 or 60 cannot be made. Nevertheless, an open wire segment 56 and an adjacent stuck-open cross-point CIP 59 or 60 are equivalent faults making such a determination unnecessary. Similarly, if the fault status data indicates that the open fault is in wire segment 55 which is positioned
5 between a breakpoint CIP 58 and a cross-point CIP 59 then a determination of whether the open fault resides in the wire segment 55 or adjacent breakpoint CIP 58 cannot be made. Again, however, an open wire segment 55 and an adjacent stuck open breakpoint CIP 58 are equivalent faults making such a determination unnecessary.

10 As indicated above, a wire segment for a short fault is defined to include a group of wire segments bounded by breakpoint CIPs. As shown in Figure 11, the wire segment for a short fault includes wires 55, 56, and 57. This is because a short fault, such as short 67, between wires 55 and 68 affect wire segments 55, 56, and 57 which must therefore be treated as a single
15 faulty segment. This is due in part to the fact that further reconfigurations and testing are generally ineffective to identify the faulty interconnect resource, i.e., whether the short is in a wire or a CIP. For example, when the fault status data indicates a short between two wires connected by a CIP, a determination as to whether a short fault between the wires exists or whether
20 the CIP is stuck-closed cannot be made. Shorted wires which are not connected by a CIP, such as wires 55 and 68 in Figure 11 however, can be further diagnosed by seeing that each wire is fully functional while the other segment it is shorted to is unused. When both segments are being tested then the failure is visible and testing can determine that the fault is a short between
25 these segments.

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Upon the completion of testing of at least the interconnect resources of the FPGA within the initial self-testing area 16 and identifying the faulty interconnect resource(s), the FPGA under test 10 is reconfigured such that the functions of the PLBs forming a portion of the working area 18 are copied to the PLBs forming the initial self-testing area 16 and the programmable interconnect resources appropriately re-routed. Once completed, the copied portion of the working area becomes a subsequent self-testing area. Preferably, the initial self-testing area 16 is reconfigured as an adjacent portion of the working area, i.e., the programmed function of an adjacent portion of the working area is relocated or more specifically, copied to the initial self-testing area 16, and the adjacent portion of the working area is reconfigured as the subsequent self-testing area. The present preferred method of roving the self-testing area 16 and reconfiguring the FPGA under test 10 is described in detail in the above-referenced U.S. Application No. 09/405,958 and in M. ABRAMOVICI ET AL., *Using Roving STARS for On-Line Testing and Diagnosis of FPGAs in Fault-Tolerant Applications*, PROC. INTN'L TEST CONF., pp. 973-982, 1999 incorporated herein by reference.

In accordance with the present inventive method, the programmable interconnect resources of subsequent self-testing areas are similarly tested and faulty resources identified, if required, as described above for the initial self-testing area 16 until each portion of the FPGA under test 10 is reconfigured as a subsequent self-testing area and at least its interconnect resources tested. In other words, the self-testing area may continuously rove around the FPGA under test 10 repeating the steps of configuring, testing, and identifying so long as the FPGA under test 10 is in operation. Advantageously, normal

operation of the FPGA under test 10 continues uninterrupted by the testing conducted within the self-testing areas.

In summary, the method of identifying faulty programmable routing resources in field programmable gate arrays may be carried out during normal on-line operation of an FPGA under test and/or during manufacturing testing by configuring FPGA resources into a working area and a self-testing area. The working area maintains normal operation of the FPGA throughout testing. During manufacturing testing, the working area may be replaced with additional self-testing areas or the self-testing area extended to include the entire FPGA. Within the initial and subsequent self-testing areas, however, the FPGA interconnect resources are reconfigured as testing regions which include groups of wires under test. The groups of wires under test are comparatively tested to determine whether a fault exists within either of the groups of wires under test. The FPGA resources within the group of wires under test identified to include a faulty interconnect resource are reconfigured, or subdivided, into subsequent groups of wires under test for further testing in order to minimize a region of the group of wires under test which includes the faulty resource and to identify a wire within the minimized region which includes the faulty resource. The FPGA resources within the self-testing area are again reconfigured to test the interconnect resources, i.e., the wire segments and/or configurable interconnect points, within the minimized region of the identified wire in order to identify the faulty interconnect resource(s). Specifically, portions of the faulty region of the identified wire are re-routed using known fault-free wires, wire segments, and/or configurable interconnect points to avoid suspect faulty wire segments

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or configurable interconnect points and further tested. These steps of re-routing and testing are repeated until the faulty wire segment, configurable interconnect point, and/or combination thereof is identified. Advantageously, the working area is substantially unaffected by testing, and testing time constraints are reduced since normal operation continues in the working area.

The foregoing description of a preferred embodiment of the present invention has been presented for purposes of illustration and description. It is not intended to be exhaustive or to limit the invention to the precise form disclosed. Obvious modifications or variations are possible in light of the above teachings. The embodiment was chosen and described to provide the best illustration of the principles of the invention and its practical application to thereby enable one of ordinary skill in the art to utilize the invention in various embodiments and with various modifications as are suited to the particular use contemplated. All such modifications and variations are within the scope of the invention as determined by the appended claims when interpreted in accordance with the breadth to which they are fairly, legally and equitably entitled.

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